

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	5298668
<b>Application Number:</b>	10755042
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	8665
<b>Title of Invention:</b>	Integrated chip package structure using silicon substrate and method of manufacturing the same
<b>First Named Inventor/Applicant Name:</b>	Mou-Shiung Lin
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<b>Attorney Docket Number:</b>	MEGP0004USA1
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<b>Application Type:</b>	Utility under 35 USC 111(a)

### Payment information:

Submitted with Payment	no
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### File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed (SB/08)	618746.PDF	738682 5452bf5c1326fe127eab04fe5781f5d96b852c84	no	4

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2	Foreign Reference	TW_531854.pdf	1757971 a2637e2d063d87f453fef9c158d502bce57b286c	no	32
<b>Warnings:</b>					
<b>Information:</b>					
3	NPL Documents	NPL1.PDF	530067 b84eccd37953b5bf2bd42c518e86a3907769a92c	no	3
<b>Warnings:</b>					
<b>Information:</b>					
4	NPL Documents	NPL2.PDF	1433670 a1990a68fa3e1e621fa33a6b7ffcec77afc6db2c	no	7
<b>Warnings:</b>					
<b>Information:</b>					
5	NPL Documents	NPL3.pdf	725052 076e0f599ecf871d34e3dba0dc38cad0f4c7a36e	no	4
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<b>Total Files Size (in bytes):</b>				5185442	

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If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

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**New International Application Filed with the USPTO as a Receiving Office**

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